

MOUNTING TEMPERATURE PROFILE (REFERENCE) 5S AT 260°C TEMP[℃] 1 260 240 + 230°C 220 . PREHEATING 200 + (130~180°) 180 160 -140 120 60S MAX 120S MAX 100 TIME ->

NOTE

1. MOUNTING TEMPERATURE PROFILE VARIES ACCORDING TO BOARD SIZE, SOLDER TYPE AND SOLDER THICKNESS. 2. UP TO 2 CYCLES OF REFLOW.

Rohs Compliant

В

2	BRASS		GOLD PLATING									
	DINNOU		UVLU FLATINU									
1	PHOSPHOR BRONZE		SILVER PLATING				3	LCP	(BEIGE), UL94V-0			
NO.	MATERIAL		FINISH , REMARKS				NO.	MA	ERIAL FINISH, REM		ARKS	
UNIT	[\$ \ \ \ \	1 S	CALE COUNT DESCRIPTION 0:1			PTION	OF REV	ISIONS	DESIGNED		CHECKED	DATE
m m		J 1										
		APPROVED : MH. YAMANE			11. ′	1.15 DRAWING		EDC3-302540-01				
Н	T HIRO	FIROSE ELECTRIC CO. LTD.		CHECKED : NK. NINOMIYA			11. 14 🖯	PART				
П				DESIGNED : YI. FUNADA			1. 10 NO.		U. FL-R-SMT-1(01)			
	<u> </u>	LID.	DRAWN	: YI. FUNADA		11.	11. 10	CODE NO.	CL331-0472-2-01		$ \wedge 1 \rangle$	
			1	6	1			7			0	

FORM HC0011-5-7 1 2 3 4

WATER SPLACHED AND CONDENSATION PLACES, PLACE ATTENTION REQUIRED: HARSH TEMPERATURE CHANGE,